

VAD 3/28/07  
14

**Please AMEND paragraph on page 47, line 15 to page 48, line 12, with the following amended paragraph:**

The moving part 1 and the fixed part 2 each comprise a kinematic mount 62, so that the moving part 1 can be positioned with respect to the fixed part 2. However, the kinematic mount 62 has a positioning accuracy of about several hundreds nm, and therefore is not ~~insufficient~~ sufficient as means for positioning the moving part 1 for which a positioning accuracy in the order of nanometers is required. Thus, the moving part 1 is aligned with respect to the fixed part 2 using a positioning sensor 63[,] as the noncontacting instrumentation means 65 of the 25 positioning sensor 63, an electric capacity sensor, an eddy current sensor, a differential trans displacement sensor, and/or laser interferometer and the like can be considered. In this case, the electric capacity sensor is used. The accuracy of the electric capacity sensor has an accuracy of several tens nm. As shown in FIG. 17, a sensor target 64 is provided on the moving part 1 side, and the electric capacity sensor is provided on the fixed part 2 side. The positioning sensor 63 is provided so that the moving part 1 can be positioned with respect to the X, Y and Z directions of the fixed part 2. Here, three positioning sensors are used, but any other number of positioning sensors may be used as necessary.

**Please AMEND paragraph on page 53, line 5 to page 54, line 2, with the following amended paragraph:**

If a body to be processed (wafer, etc.) is exposed using the exposure apparatus, it is usually expected that the temperature of the optical element 32 is increased due to exposure heat as described previously. If the temperature of the optical element 32 is increased to the extent that a certain amount of deformation is exceeded, a correct relation of image formation